



## Product Information Sheet

### EPO-TEK® OH108-1

**Date:** September 2017  
**Rev:** III  
**No. of Components:** Two  
**Mix Ratio by Weight:** 10 : 1  
**Specific Gravity:** Part A: 1.13 Part B: 1.02  
**Pot Life:** 4 Hours  
**Shelf Life- Bulk:** One year at room temperature

**Recommended Cure: 150°C / 1 Hour**

Minimum Alternative Cure(s):

*May not achieve performance properties listed below*

150°C / 1 Minute

80°C / 30 Minutes

#### NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

**Product Description:** A two component, slightly electrically conductive epoxy suggested for EMI and Rf shielding of sensor devices including IR detectors. Low viscosity, black color, IR opaque, fast cure, and reasonable pot-life are few of its traits. It was designed for adhering filter windows to opto-hybrids or the cap of TO-cans.

**Typical Properties:** Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Black	Part B: Amber	
* Consistency:	Pourable liquid		
* Viscosity (23°C) @ 100 rpm:	750 - 1,250	cPs	
Thixotropic Index:	N/A		
* Glass Transition Temp:	≥ 80	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	54	x 10 <sup>-6</sup> in/in°C
	Above Tg:	154	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	75		
Lap Shear @ 23°C:	1,072	psi	
Die Shear @ 23°C:	≥ 20	Kg	7,112 psi
Degradation Temp:	375	°C	
Weight Loss:			
	@ 250°C:	0.27	%
Suggested Operating Temperature:	< 300	°C (Intermittent)	
Storage Modulus:	237,760	psi	
* Particle Size:	≤ 20	microns	
ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	N/A		
Volume Resistivity @ 23°C:	1	KOhm-cm	
OPTICAL PROPERTIES @ 23°C:			
Spectral Transmission:	< 1% @ 300-2000	nm	
Refractive Index:	N/A		

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

EPOXY TECHNOLOGY, INC.

14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782

[www.epotek.com](http://www.epotek.com)